

RESPONSE TO OFFICE ACTION**Serial No. 09/921,588****Page 3 of 5****In the Specification:**

Please amended paragraph [0015] as follows:

Fig. 1 depicts one embodiment of a polishing system 100 for polishing a substrate 112 having a polishing fluid delivery system 102 that controls the distribution of polishing fluid 114 across a polishing material 108. Examples of polishing systems which may be adapted to benefit from aspects of the invention are disclosed in United States Patent Application No. ~~09/144,456~~ 09/244,456, now Patent No. 6,244,935, filed February 4, 1999 by Birang, et al. and United States Patent No. 5,738,574, issued April 14, 1998 to Tolles, et al., both of which are hereby incorporated by reference in their entirety. Although the polishing fluid delivery system 102 is described in reference to the illustrative polishing system 100, the invention has utility in other polishing systems that process substrates in the presence of a polishing fluid.

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